

POGO PIN COOLING SYSTEM AND METHOD AND ELECTRONIC DEVICE TESTING APPARATUS HAVING THE SYSTEM

Abstract

The present invention relates to a pogo pin cooling system and a pogo pin cooling method and an electronic device testing apparatus having the system. The system uses a cooling fluid supply module for the cooling of the pogo pin, and the cooling fluid may be either a coolant or a cooling gas. When an electronic device is accommodated in the chip socket, the cooling fluid supply module supplies a cooling fluid into the chip socket through the cooling fluid supply channel and the inlet, and the cooling fluid passes through the pogo pins and then flows into the cooling fluid discharge channel through the outlet. In the present invention, the cooling fluid is mainly used to cool not only the pogo pins in the chip socket but also the bottom surface of the electronic device and the solder ball contacts on the bottom surface.

(Fig. 1)